L Number	Hits	Search Text	DB	Time stamp
1	1	"6131088"	JPO;	2004/06/28
2	2	"61031088"	DERWENT JPO; DERWENT	17:00 2004/06/28 17:00
3	1	"06131088"	JPO; DERWENT	2004/06/28 17:00
4	0	"406131088"	JPO; DERWENT	2004/06/28
_	210846	(chip or die or device or package) and (substrate or board or pcb or pwb) and (adhesive or bonding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/28 14:38
_	85527	((chip or die or device or package) and (substrate or board or pcb or pwb) and (adhesive or bonding)) and (@ad<19960905)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/28 14:36
-	312	<pre>(((chip or die or device or package) and (substrate or board or pcb or pwb) and (adhesive or bonding)) and (@ad<19960905)) and (((adhesive or bonding) and (stress or deformation or cte)) with (change or shape))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 14:43
-	491	<pre>(((chip or die or device or package) and (substrate or board or pcb or pwb) and (adhesive or bonding)) and (@ad<19960905)) and (((adhesive or bonding) and (stress or deformation or cte or expansion or shrink or shrinkage)) with (change or shape))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 12:56
-	232	((((chip or die or device or package) and (substrate or board or pcb or pwb) and (adhesive or bonding)) and (@ad<19960905)) and (((adhesive or bonding) and (stress or deformation or cte or expansion or shrink or shrinkage)) with (change or shape))) and ((adhesive or bonding) same (gap or gaps or space or spaces or bubble or void or voids or vacuum))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 14:32
-	2978	((adhesive or bonding) and (deform or deformable or shange or shape)) with air	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/28
-	1496	(((adhesive or bonding) and (deform or deformable or shange or shape)) with air) and (@ad<19960905)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/28 14:43
_	200	<pre>((((adhesive or bonding) and (deform or deformable or shange or shape)) with air) and (@ad<19960905)) and (chip or die or device or package) and (substrate or board or pcb or pwb)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/28 14:37
_	194	((((adhesive or bonding) and (deform or deformable or shange or shape)) with air) and (@ad<19960905)) and (chip or die or device or package) and (substrate or board or pcb or pwb)) not ((((chip or die or device or package) and (substrate or board or pcb or pwb) and (adhesive or bonding)) and (@ad<19960905)) and (((adhesive or bonding) and (stress or deformation or cte or expansion or shrink or shrinkage)) with (change or shape))) and ((adhesive or bonding) same (gap or gaps or space or spaces or bubble or void	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 14:37
		or voids or vacuum)))		

		[[[[[]]]]]]]] [[[]]]]	HCDNE	2004/06/20
-	68	(((((adhesive or bonding) and (deform or	USPAT;	2004/06/28
		deformable or shange or shape)) with air	US-PGPUB;	14:38
) and (@ad<19960905)) and (chip or die	EPO; JPO;	
		or device or package) and (substrate or	DERWENT;	
		board or pcb or pwb)) not ((((chip or	IBM_TDB	
		die or device or package) and (substrate		
		or board or pcb or pwb) and (adhesive or		
		bonding)) and (@ad<19960905)) and		
		(((adhesive or bonding) and (stress or		
		deformation or cte or expansion or shrink		
		or shrinkage)) with (change or shape)))		
		and ((adhesive or bonding) same (gap or		
		gaps or space or spaces or bubble or void		İ
		or voids or vacuum)))) and ((chip or die		
		or device or package) with (adhesive or		
		bonding))		
-	0	257/783.ccls and ((adhesive or bonding)	USPAT;	2004/06/28
		and (deform or deformable or shange or	US-PGPUB;	14:42
		shape)) with air	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	257/783.ccls. and ((adhesive or bonding)	USPAT;	2004/06/28
		and (deform or deformable or shange or	US-PGPUB;	14:42
		shape)) with air	EPO; JPO;	•
		-	DERWENT;	
			IBM TDB	
-	18	257/783.ccls. and (((adhesive or bonding)	USPAT;	2004/06/28
		and (stress or deformation or cte)) with	US-PGPUB;	14:45
		(change or shape))	EPO; JPO;	
		-	DERWENT;	
			IBM TDB	
-	2	(257/783.ccls. and (((adhesive or	USPAT;	2004/06/28
		bonding) and (stress or deformation or	US-PGPUB;	14:43
		cte)) with (change or shape))) and	EPO; JPO;	
		(@ad<19960905)	DERWENT;	
			IBM TDB	
-	5	257/795.ccls. and (((adhesive or bonding)	USPAT;	2004/06/28
		and (stress or deformation or cte)) with	US-PGPUB;	16:59
	:	(change or shape))	EPO; JPO;	
		· · · · · · · · · · · · · · · · · · ·	DERWENT;	
			IBM TDB	